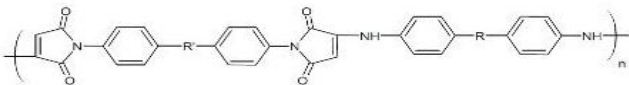




Polyimide Resin Powder

PIR-003 Polyimide Resin is unfilled bismaleimide-based soluble polyimide resin powder with excellent heat stability, mechanical and dielectric strength, radiation and chemical resistance, etc.

Base structure:



Application: matrix resin for reinforcement prepreg of fibers(carbon, glass, etc.), mixture with epoxy for heat resistance, membrane, etc. Before use, dissolve in DMF, etc. for a certain solid content solution.

Properties:

Visual/Solubility	Fine yellow powder/soluble in DMF,NMP,etc.
Purity%	Over 98.5
Gravity	1.32g/cm ³
Gelling time(170℃)	200--500s
Curing temperature(℃)/Pressure(MPa)	220-230/30-60
Softening temperature (℃)	90-120
Martin temperature (℃)	260
TGA260 (℃) 24hr/300 (℃) 24hr	Less 1.5% (mainly moisture loss)
Tg (℃)	330
Tensile strength(MPa)	113.4
Elongation%	Over 5%
Surface resistivityΩ	1 x 10 ¹⁵
Dielectric constant	3.5

Packing: carton after sealed by plastic film bag Shelf life: 2 Years

Note: 1.Since polyimide resins are hygroscopic, please predried at 250 °F (120 °C) for a couple of hours before any use

2.All of above information is based on our best knowledge, not read as guarantees. Right reserved for corrections.

3.Please contact us if customization requirements.

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